# 捷多邦,专业PCB打样工厂,24小时加急**企業29FCT520T**MULTILEVEL PIPELINE REGISTER WITH 3-STATE OUTPUTS

D, P, OR SO PACKAGE

SCCS011C - MAY 1994 - REVISED NOVEMBER 2001

- Function, Pinout, and Drive Compatible
   With FCT, F Logic, and AM29520
- Reduced V<sub>OH</sub> (Typically = 3.3 V) Version of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)
- Single- and Dual-Pipeline Operation Modes
- Multiplexed Data Inputs and Outputs
- CY29FCT520T
  - 64-mA Output Sink Current
     32-mA Output Source Current
- CY29FCT520ATDMB, CY29FCT520BTDMB
  - 32-mA Output Sink Current
     12-mA Output Source Current
- 3-State Outputs

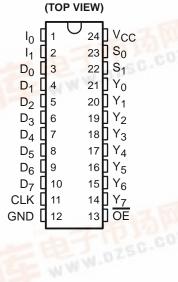
#### description

The CY29FCT520T is a multilevel 8-bit-wide pipeline register. The device consists of four registers, A1, A2, B1, and B2, which are configured by the instruction inputs  $I_0$ ,  $I_1$  as a single four-level pipeline or as two two-level pipelines. The contents of any register can be read at the multiplexed output at any time by using the multiplex-selection controls ( $S_0$  and  $S_1$ ).

The pipeline registers are positive-edge triggered, and data is shifted by the rising edge of the clock input. Instruction I = 0 selects the four-level pipeline mode. Instruction I = 1 selects the two-level B pipeline, while I = 2 selects the two-level A pipeline. I = 3 is the hold instruction; no shifting is performed by the clock in this mode.

In the two-level operation mode, data is shifted from level 1 to level 2 and new data is loaded into level 1.

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.



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Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

# CY29FCT520T MULTILEVEL PIPELINE REGISTER WITH 3-STATE OUTPUTS SCCS011C - MAY 1994 - REVISED NOVEMBER 2001

#### PIPELINE INSTRUCTION TABLE

I =	= 0	I = 1			I=	: 3		
l <sub>1</sub> = 0	I <sub>0</sub> = 0	I <sub>1</sub> = 0	l <sub>0</sub> = 1	l <sub>1</sub> = 1	l <sub>0</sub> = 0	l <sub>1</sub> = 1	l <sub>0</sub> = 1	
A1 A2	B1 B2	A1 A2	B1 B2	A1 A2	B1	A1	B1	
Single fo	our-level		Dual tw	o-level		Hold		

#### **ORDERING INFORMATION**

TA	PAC	KAGE†	SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	SOIC - SO	Tube	6.0	CY29FCT520CTSOC	29FCT520C
	3010 - 30	Tape and reel	6.0	CY29FCT520CTSOCT	29FC1520C
	SOIC - SO	Tube	7.5	CY29FCT520BTSOC	29FCT520B
-40°C to 85°C	3010 - 30	Tape and reel	7.5	CY29FCT520BTSOCT	29FC1520B
	DIP – P	Tube	14.0	CY29FCT520ATPC	CY29FCT520ATPC
	SOIC - SO	Tube		CY29FCT520ATSOC	29FCT520A
	3010 - 30	Tape and reel	14.0	CY29FCT520ATSOCT	29FC1520A
–55°C to 125°C	CDIP – D	Tube	8.0	5962-9220504MLA (CY29FCT520BTDMB)	
-55°C (0 125°C	CDIF - D	Tube	16.0	5962-9220502MLA (CY29FCT520ATDMB)	

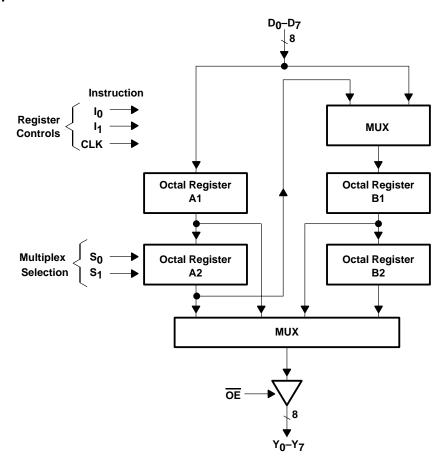
<sup>†</sup> Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

#### **FUNCTION TABLE**

INP	UTS	ОИТРИТ
S <sub>1</sub>	s <sub>0</sub>	OUTFUT
1	1	A1
1	0	A2
0	1	B1
0	0	B2



#### logic diagram



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range to ground potential	–0.5 V to 7 V
DC input voltage range	–0.5 V to 7 V
DC output voltage range	–0.5 V to 7 V
DC output current (maximum sink current/pin)	120 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 1): P package	67°C/W
(see Note 2): SO package	46°C/W
Ambient temperature range with power applied, T <sub>A</sub>	–65°C to 135°C
Storage temperature range, T <sub>stq</sub>	−65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The package thermal impedance is calculated in accordance with JESD 51-3.

2. The package thermal impedance is calculated in accordance with JESD 51-7.



#### CY29FCT520T MULTILEVEL PIPELINE REGISTER WITH 3-STATE OUTPUTS

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#### recommended operating conditions (see Note 3)

		CY29FCT520ATDMB CY29FCT520BTDMB			CY29FCT520T			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Vcc	Supply voltage	4.5	5	5.5	4.75	5	5.25	V
$V_{IH}$	High-level input voltage	2			2			V
VIL	Low-level input voltage			8.0			0.8	V
loh	High-level output current			-12			-32	mA
lOL	Low-level output current			32			64	mA
TA	Operating free-air temperature	-55		125	-40		85	°C

NOTE 3: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		FCT520A FCT520B		CY	29FCT52	от	UNIT
		MIN	TYP <sup>†</sup>	MAX	MIN	TYP <sup>†</sup>	MAX	
Vina	$V_{CC} = 4.5 \text{ V}, \qquad I_{IN} = -18 \text{ mA}$		-0.7	-1.2				V
VIK	$V_{CC} = 4.75 \text{ V}, \qquad I_{IN} = -18 \text{ mA}$					-0.7	-1.2	٧
	$V_{CC} = 4.5 \text{ V}, \qquad I_{OH} = -12 \text{ mA}$	2.4	3.3					
Voн	V <sub>CC</sub> = 4.75 V				2.4	3.3		V
	$I_{OH} = -32 \text{ mA}$				2			
\/o:	$V_{CC} = 4.5 \text{ V}, \qquad I_{OL} = 32 \text{ mA}$		0.3	0.55				٧
VOL	$V_{CC} = 4.75 \text{ V},  I_{OL} = 64 \text{ mA}$					0.3	0.55	٧
$V_{hys}$	All inputs		0.2			0.2		V
	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = V_{CC}$			5				μΑ
ΙΙ	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = V_{CC}$						5	μΑ
lu.	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$			±1				μА
ΊΗ	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$						±1	μΛ
lu.	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$			±1				μΑ
۱۱۲	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$						±1	μΑ
l <sub>off</sub>	$V_{CC} = 0 \text{ V}, \qquad V_{OUT} = 4.5 \text{ V}$			±1			±1	μΑ
1+	$V_{CC} = 5.5 \text{ V}, \qquad V_{OUT} = 0 \text{ V}$	-60	-120	-225				mA
los‡	$V_{CC} = 5.25 \text{ V}, \qquad V_{OUT} = 0 \text{ V}$				-60	-120	-225	ША
lozu	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$			10				μΑ
IOZH	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 2.7 \text{ V}$						10	μΑ
lozi	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$			-10				μА
lozL	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} = 0.5 \text{ V}$						-10	μΑ
loo	$V_{CC} = 5.5 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}, \qquad V_{IN} \ge V_{CC} - 0.3 \text{ V}$	2 V	0.1	0.2				mA
lcc	$V_{CC} = 5.25 \text{ V}, \qquad V_{IN} \le 0.2 \text{ V}, \qquad V_{IN} \ge V_{CC} - 0.3$					0.1	0.2	ША
ΔlCC	$V_{CC} = 5.5 \text{ V}, V_{IN} = 3.4 \text{ V}, f_1 = 0, Outputs open$		0.5	2				mA
ΔiCC	$V_{CC} = 5.25 \text{ V}, V_{IN} = 3.4 \text{ V}$ , $f_1 = 0$ , Outputs open					0.5	2	1117

<sup>†</sup> Typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

<sup>§</sup> Per TTL-driven input (VIN = 3.4 V); all other inputs at VCC or GND



Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, Ios tests should be performed last.

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# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

PARAMETER	TEST CONDITIONS				CT520A		CY	29FCT52	0Т	UNIT
				MIN	TYP	MAX	MIN	TYP†	MAX	
la a = ¶	$V_{CC} = 5.5 \text{ V}$ , Ou One bit switching $V_{IN} \le 0.2 \text{ V}$ or $V_{I}$		0.06	0.12				mA/		
ICCD¶	$V_{CC}$ = 5.25 V, Outputs open, One bit switching at 50% duty cycle, $\overline{OE}$ = GND, $V_{IN} \le 0.2 \text{ V or } V_{IN} \ge V_{CC} - 0.2 \text{ V}$			0.06	0.12	MHz				
		One bit switching at f <sub>1</sub> = 5 MHz at	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		0.7	1.4				
	V <sub>CC</sub> = 5.5 V, Outputs open, f <sub>0</sub> = 10 MHz, OE = GND	50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$		1.2	3.4				
		Eight bits switching at f <sub>1</sub> = 5 MHz at	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$		2.8	5.6				
. #		50% duty cycle	V <sub>IN</sub> = 3.4 V or GND		5.1	14.3				
lC#		One bit switching at f <sub>1</sub> = 5 MHz at	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					0.7	1.4	mA
	V <sub>CC</sub> = 5.25 V, Outputs open,	50% duty cycle	$V_{IN} = 3.4 \text{ V or GND}$					1.2	3.4	
	$f_0 = 10 \text{ MHz},$ OE = GND	Eight bits switching at	$V_{IN} \le 0.2 \text{ V or}$ $V_{IN} \ge V_{CC} - 0.2 \text{ V}$					2.8	5.6	
		f <sub>1</sub> = 5 MHz at 50% duty cycle	V <sub>IN</sub> = 3.4 V or GND		·			5.1	14.3	
C <sub>i</sub>		-			5	10		5	10	pF
Co					9	12		9	12	pF

<sup>†</sup> Typical values are at  $V_{CC} = 5 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ .

Where:

I<sub>C</sub> = Total supply current

ICC = Power-supply current with CMOS input levels

 $\Delta I_{CC}$  = Power-supply current for a TTL high input ( $V_{IN} = 3.4 \text{ V}$ )

D<sub>H</sub> = Duty cycle for TTL inputs high N<sub>T</sub> = Number of TTL inputs at D<sub>H</sub>

ICCD = Dynamic current caused by an input transition pair (HLH or LHL)

f<sub>0</sub> = Clock frequency for registered devices, otherwise zero

f<sub>1</sub> = Input signal frequency

 $N_1$  = Number of inputs changing at  $f_1$ 

All currents are in milliamperes and all frequencies are in megahertz.

 $\parallel$  Values for these conditions are examples of the I<sub>CC</sub> formula.

This parameter is derived for use in total power-supply calculations.

 $<sup>^{\#}</sup>$ IC = ICC +  $\triangle$ ICC  $\times$  D<sub>H</sub>  $\times$  N<sub>T</sub> + ICCD (f<sub>0</sub>/2 + f<sub>1</sub>  $\times$  N<sub>1</sub>)

#### CY29FCT520T MULTILEVEL PIPELINE REGISTER WITH 3-STATE OUTPUTS

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### timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

			CY29FCT520	ATDMB	CY29FCT520	ВТОМВ	UNIT
			MIN	MAX	MIN	MAX	UNIT
t <sub>W</sub>	Pulse duration, CLK high or low		8		6		ns
	Output the a haden OUK	Data	6		2.8		no
t <sub>su</sub>	Setup time, before CLK↑	I	6		4.5		ns
4.	Hold time, after CLK↑	Data	2	·	2		no
th	Hold time, after CLK	I	2		2		ns

# timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

				CY29FCT520AT		520BT	CY29FCT520CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	UNIT
t <sub>W</sub>	Pulse duration, CLK high or low		7		5.5		5.5		ns
Γ.	Outurn these had are OLIVA	Data	5		2.5		2.5		20
t <sub>su</sub>	Setup time, before CLK↑	I	5		4		4		ns
4.	Hold time ofter CLIV	Data	2		2		2		no
th	Hold time, after CLK↑	I	2		2		2		ns

#### switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY29FCT520	DATDMB	CY29FCT52	UNIT		
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	ONT	
<sup>t</sup> PLH	CLK	<b>V</b>	2	16	2	8		
t <sub>PHL</sub>	OLK	ı	2	16	2	8	ns	
<sup>t</sup> PLH	S <sub>0</sub> or S <sub>1</sub>	V	2	15	2	8	ns	
t <sub>PHL</sub>	30 01 31	•	2	15	2	8	115	
<sup>t</sup> PHZ	ŌĒ	V	1.5	13	1.5	7.5	ns	
t <sub>PLZ</sub>	OE	Y	1.5	13	1.5	7.5	110	
<sup>t</sup> PZH	ŌĒ	V	1.5	16	1.5	8	no	
<sup>t</sup> PZL	OE	ī	1.5	16	1.5	8	ns	

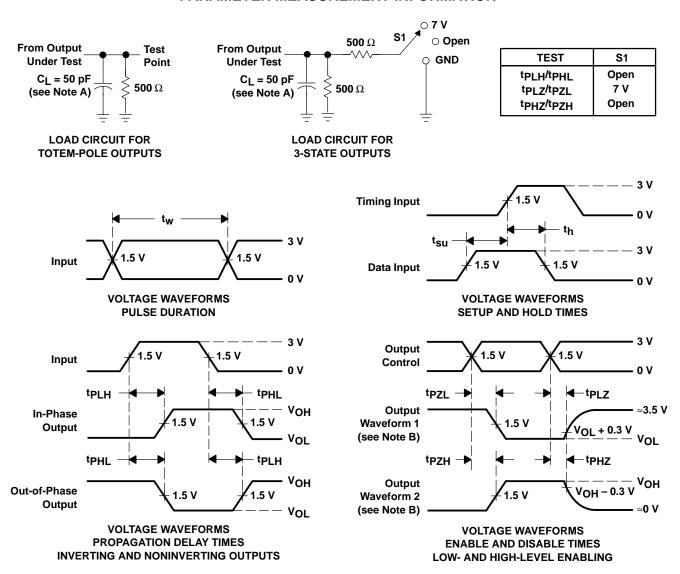
#### switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM	то	CY29FCT520AT		CY29FCT520BT		CY29FCT520CT		UNIT
PARAMETER	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	UNIT
<sup>t</sup> PLH	CLK	V	2	14	2	7.5	2	6	ne
<sup>t</sup> PHL	CLK	Y	2	14	2	7.5	2	6	ns
<sup>t</sup> PLH	Sa or S.	V	2	13	2	7.5	2	6	20
<sup>t</sup> PHL	S <sub>0</sub> or S <sub>1</sub>	T	2	13	2	7.5	2	6	ns
<sup>t</sup> PHZ	ŌĒ	V	1.5	12	1.5	7	1.5	6	20
<sup>t</sup> PLZ	OE .	Y	1.5	12	1.5	7	1.5	6	ns
<sup>t</sup> PZH	ŌĒ	V	1.5	15	1.5	7.5	1.5	6	ne
<sup>t</sup> PZL	]	l r	1.5	15	1.5	7.5	1.5	6	ns



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#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms







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#### **PACKAGING INFORMATION**

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
5962-9220502MLA	ACTIVE	CDIP	JT	24	1	TBD	Call TI	Level-NC-NC-NC
5962-9220504MLA	ACTIVE	CDIP	JT	24	1	TBD	Call TI	Level-NC-NC-NC
CY29FCT520ATPC	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CY29FCT520ATPCE4	ACTIVE	PDIP	NT	24	15	Pb-Free (RoHS)	CU NIPDAU	Level-NC-NC-NC
CY29FCT520ATSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY29FCT520ATSOCE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY29FCT520ATSOCT	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY29FCT520ATSOCTE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY29FCT520BTSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY29FCT520BTSOCE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY29FCT520BTSOCT	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY29FCT520BTSOCTE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY29FCT520CTSOC	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY29FCT520CTSOCE4	ACTIVE	SOIC	DW	24	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY29FCT520CTSOCT	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY29FCT520CTSOCTE4	ACTIVE	SOIC	DW	24	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>&</sup>lt;sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free** (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is



#### **PACKAGE OPTION ADDENDUM**

21-Nov-2005

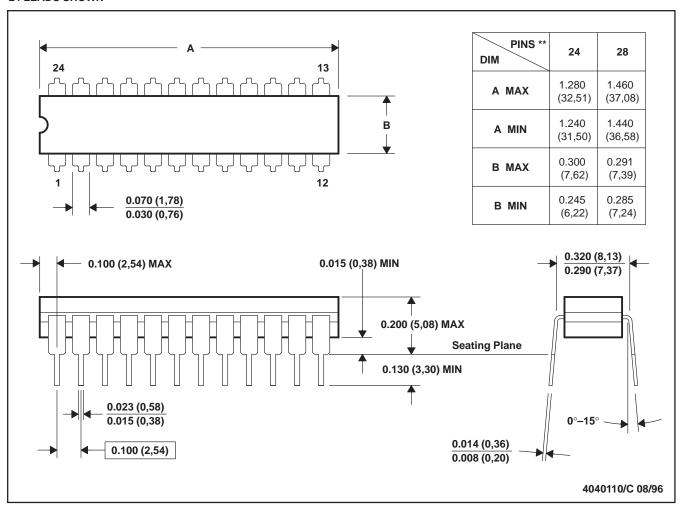
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#### JT (R-GDIP-T\*\*)

#### 24 LEADS SHOWN

#### **CERAMIC DUAL-IN-LINE**



NOTES: A. All linear dimensions are in inches (millimeters).

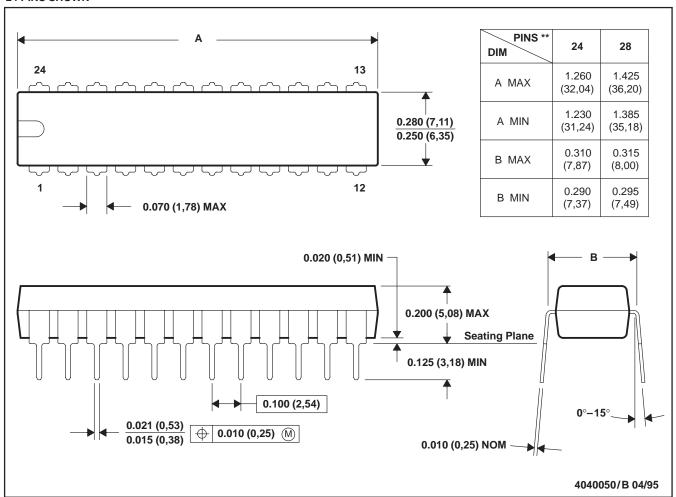
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP3-T24, GDIP4-T28, and JEDEC MO-058 AA, MO-058 AB



#### NT (R-PDIP-T\*\*)

#### PLASTIC DUAL-IN-LINE PACKAGE

#### **24 PINS SHOWN**

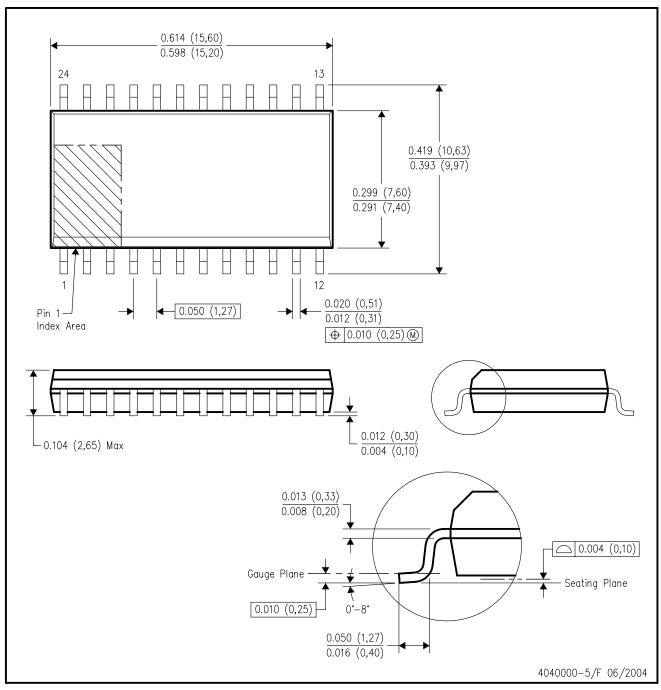


NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

#### DW (R-PDSO-G24)

#### PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AD.



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